



Vishay Siliconix

P-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)		
- 40	0.045 at V _{GS} = - 10 V	- 7.2	11.8 nC		
- 40	0.062 at V _{GS} = - 4.5 V	- 6.1	11.0110		

SO-8 S 1 S 2 T D G 4 SO-8

FEATURES

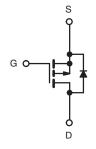
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load Switches, Adaptor Switch
 - Notebook PCs



P-Channel MOSFET

Ordering Information: Si4447ADY-T1-GE3	(Lead ((Ph)-free and Halogen-free)
Ordering information. Sifff ADI-11-GLS	(Leau ((i b)-iiee and malogen-iiee)

Top View

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 40	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		- 7.2		
Continuous Dunin Courset /T 450 °C)	T _C = 70 °C		- 5.7		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 5.5 ^{a, b}		
	T _A = 70 °C		- 4.4 ^{a, b}	_	
Pulsed Drain Current	I _{DM}	- 20	Α		
Continuous Course Dunin Diado Current	T _C = 25 °C		- 3.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _s	- 2.1 ^{a, b}		
Avalanche Current		I _{AS}	- 10		
Single-Pulse Avalanche Energy		E _{AS}	5	mJ	
	T _C = 25 °C		4.2		
Mariana Barra Birata dia	T _C = 70 °C		2.7	\A/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C		1.6 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under steady state conditions is 85 $^{\circ}\text{C/W}.$
- d. Based on $T_C = 25$ °C.

Si4447ADY

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	- 40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 42		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.2		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7 0	I _{DSS}	V _{DS} = - 40 V, V _{GS} = 0 V			- 1	μА	
Zero Gate Voltage Drain Current		$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 10			Α	
Durin Course On Chata Basistanasa	Б	V _{GS} = - 10 V, I _D = - 5 A		0.036	0.045	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4 A		0.050	0.062		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 5 A		14		S	
Dynamic ^b							
Input Capacitance	C _{iss}			970		pF	
Output Capacitance	C _{oss}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120			
Reverse Transfer Capacitance	C _{rss}			95			
T. 10 1 01	Qg	V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 5 A		25	38	nC	
Total Gate Charge				11.8	18		
Gate-Source Charge	Q_{gs}	$V_{DS} = -20 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		3			
Gate-Drain Charge	Q _{gd}			5.2			
Gate Resistance	R_g	f = 1 MHz	1.0	5.5	11	Ω	
Turn-On Delay Time	t _{d(on)}			7	14		
Rise Time	t _r	V_{DD} = - 20 V, R_L = 4 Ω		12	24	1	
Turn-Off DelayTime	t _{d(off)}	$I_D\cong$ - 5 A, V_{GEN} = - 10 V, R_g = 1 Ω		30	60		
Fall Time	t _f			9	18	no	
Turn-On Delay Time	t _{d(on)}			44	80	ns	
Rise Time	t _r	V_{DD} = - 20 V, R_L = 4 Ω		33	60	_	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 5 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		28	55		
Fall Time	t _f			13	25		
Drain-Source Body Diode Characteris	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 3.5		
Pulse Diode Forward Current	I _{SM}				- 20	Α	
Body Diode Voltage	V_{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.76	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 2.4 dl/dt = 100.4/up. T = 25.90		19	35	nC	
Reverse Recovery Fall Time	t_{a} $t_{F} = -2 \text{ A, dI/dt} = 100 \text{ A/µs, T}_{J} = 25 °C$			14			
Reverse Recovery Rise Time	t _b			13		ns	

Notes:

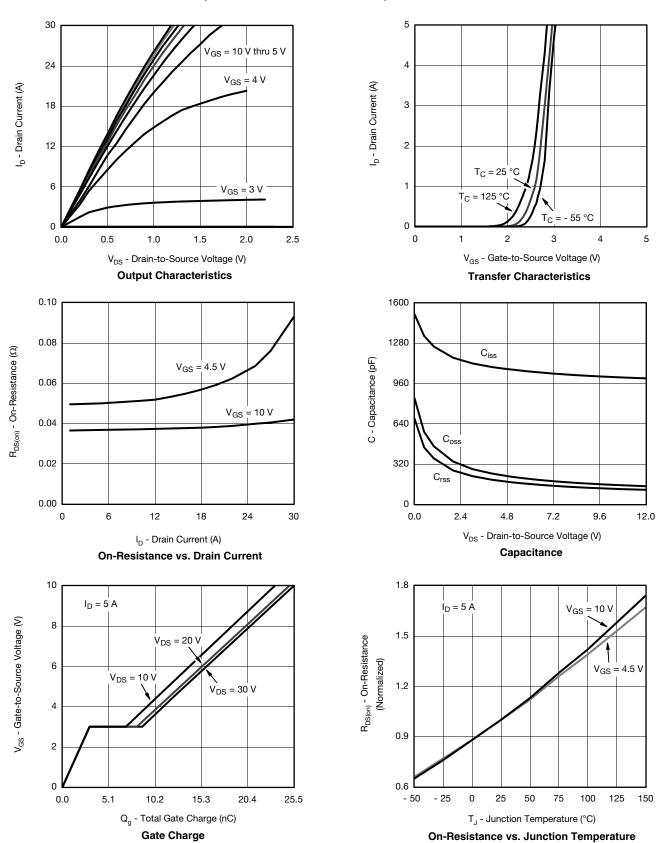
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

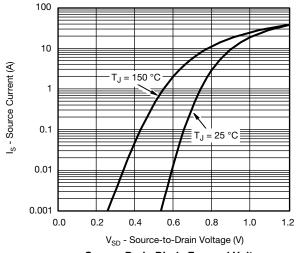


Si4447ADY

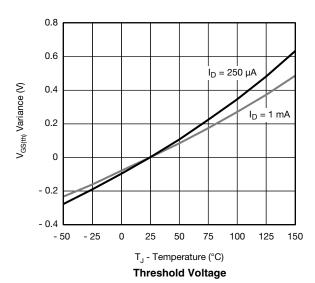
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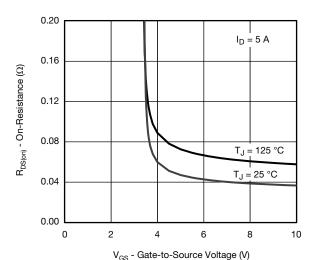
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

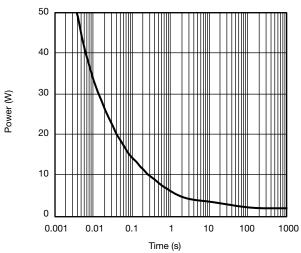


Source-Drain Diode Forward Voltage

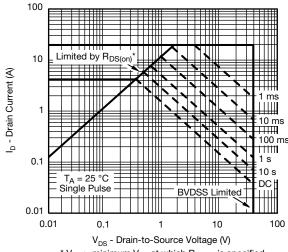




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



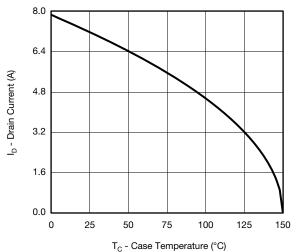
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

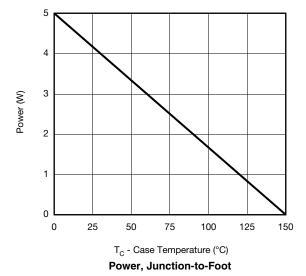


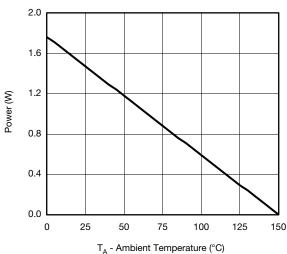
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*





Power Derating, Junction-to-Ambient

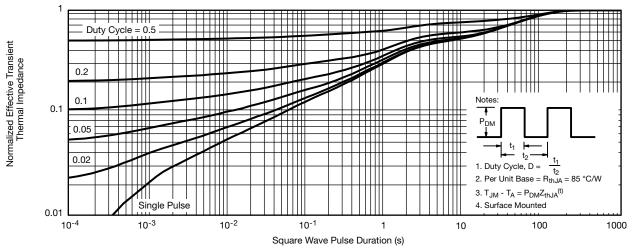
 $^{^*}$ The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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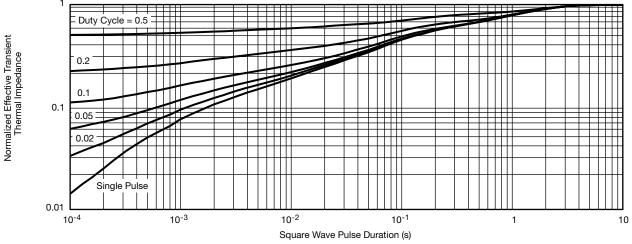
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg267189.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	MILLIMETERS INCHES				
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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